ALP: SEM	<b>HA &amp; OMEGA</b> ICONDUCTOR		<b>AOTF7N60FD</b> 600V, 7A N-Channel MOSFET with Fast Recovery Diode			
General Description			Product Summary			
The AOTF7N60FD has been fabricated using an advanced high voltage MOSFET process that is designed to deliver high levels of performance and robustness in popular AC-DC applications. By providing low $R_{DS(on)}$ , $C_{iss}$ and $C_{rss}$ along with guaranteed avalanche capability this part can be adopted quickly into new and existing offline power supply designs.			$V_{DS}$ I <sub>D</sub> (at V <sub>GS</sub> =10V) R <sub>DS(ON)</sub> (at V <sub>GS</sub> =10V)	700V@150℃ 7A < 1.45Ω		
			100% UIS Tested 100%  R <sub>g</sub> Tested	Green		
A	Top View TO-220F OTF7N60FD CotF7N60FD Ratings T <sub>A</sub> =25°C unless	othonuison	G G S			
Parameter	taings T <sub>A</sub> =25 C unles	Symbol	AOTF7N60FD	Units		
Drain-Source Voltage		V <sub>DS</sub>	600	V		
			±30	V		
Gate-Source Voltage	T <sub>c</sub> =25°C	V <sub>GS</sub>	±30 7*	V		
Continuous Drain Current	T <sub>c</sub> =100°C	I <sub>D</sub>	4.7*	A		
Pulsed Drain Current <sup>C</sup>		I <sub>DM</sub>	24			
Avalanche Current <sup>C</sup>	Avalanche Current <sup>C</sup>		3.5	А		
Repetitive avalanche energy <sup>C</sup>		E <sub>AR</sub>	184	mJ		
Single pulsed avalanche energy <sup>G</sup>		E <sub>AS</sub>	368	mJ		
Peak diode recovery dv/dt		dv/dt	5	V/ns		
Power Dissipation <sup>B</sup>	T <sub>C</sub> =25°C	PD	39	W		
	Derate above 25°C	۲D	0.3	W/ °C		
Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to 150	°C		
Maximum lead temperature for soldering						
purpose, 1/8" from case for 5 seconds		TL	300	°C		
Thermal Characteris	tics					
Parameter		Symbol	AOTF7N60FD	Units		
Maximum Junction-to-Ambient A,D		R <sub>0JA</sub>	65	°C/W		
Maximum Junction-to-Case		$R_{ ext{ heta}JC}$	3.25	°C/W		

\* Drain current limited by maximum junction temperature.



#### Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Units	
STATIC I	PARAMETERS						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> =10mA, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	600				
		$I_{D}$ =10mA, $V_{GS}$ =0V, $T_{J}$ =150°C		700		V	
BV <sub>DSS</sub> /∆TJ	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> =10mA, V <sub>GS</sub> =0V		0.68		V/°C	
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS}$ =600V, $V_{GS}$ =0V			10		
		V <sub>DS</sub> =480V, T <sub>J</sub> =125°C			100	μA	
I <sub>GSS</sub>	Gate-Body leakage current	$V_{DS}=0V, V_{GS}=\pm 30V$			±100	nA	
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS}$ =5V, $I_D$ =250 $\mu$ A	2.5	3.3	4.2	V	
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =3.5A		1.2	1.45	Ω	
<b>g</b> <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =40V, I <sub>D</sub> =3.5A		7		S	
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =7A,V <sub>GS</sub> =0V		1.03	1.6	V	
I <sub>S</sub>	Maximum Body-Diode Continuous Current				7	Α	
I <sub>SM</sub>	Maximum Body-Diode Pulsed Current				24	Α	
DYNAMI	C PARAMETERS						
C <sub>iss</sub>	Input Capacitance		600	826	995	pF	
C <sub>oss</sub>	Output Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =25V, f=1MHz	60	86	115	pF	
C <sub>rss</sub>	Reverse Transfer Capacitance		4.5	7.9	11.5	pF	
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz	2	4	6	Ω	
SWITCH	ING PARAMETERS						
Qg	Total Gate Charge		15	20	25	nC	
Q <sub>gs</sub>	Gate Source Charge	$V_{GS}$ =10V, $V_{DS}$ =480V, $I_{D}$ =7A		3.6		nC	
$Q_{gd}$	Gate Drain Charge			7.7		nC	
t <sub>D(on)</sub>	Turn-On DelayTime			24		ns	
t <sub>r</sub>	Turn-On Rise Time	$V_{GS}$ =10V, $V_{DS}$ =300V, $I_{D}$ =7A,		55		ns	
t <sub>D(off)</sub>	Turn-Off DelayTime	$R_{G}=25\Omega$		56		ns	
t <sub>f</sub>	Turn-Off Fall Time			42		ns	
t <sub>rr</sub>	Body Diode Reverse Recovery Time	I <sub>F</sub> =7A,dI/dt=100A/µs,V <sub>DS</sub> =100V		76	130	ns	
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge	e I <sub>F</sub> =7A,dI/dt=100A/μs,V <sub>DS</sub> =100V		0.3	0.5	μC	

A. The value of R  $_{\rm 0JA}$  is measured with the device in a still air environment with T  $_{\rm A}$  =25° C.

B. The power dissipation  $P_D$  is based on  $T_{J(MAX)}$ =150° C, using junction-to-case thermal resistance, and is more useful in setting the upper

dissipation limit for cases where additional heatsinking is used.

C. Repetitive rating, pulse width limited by junction temperature  $T_{J(MAX)}=150^{\circ}$  C, Ratings are based on low frequency and duty cycles to keep initial  $T_{J}=25^{\circ}$  C.

D. The R  $_{\rm 0JA}$  is the sum of the thermal impedance from junction to case R  $_{\rm 0JC}$  and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300 µs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsin k, assuming a maximum junction temperature of  $T_{J(MAX)}$ =150° C. The SOA curve provides a single pulse rating.

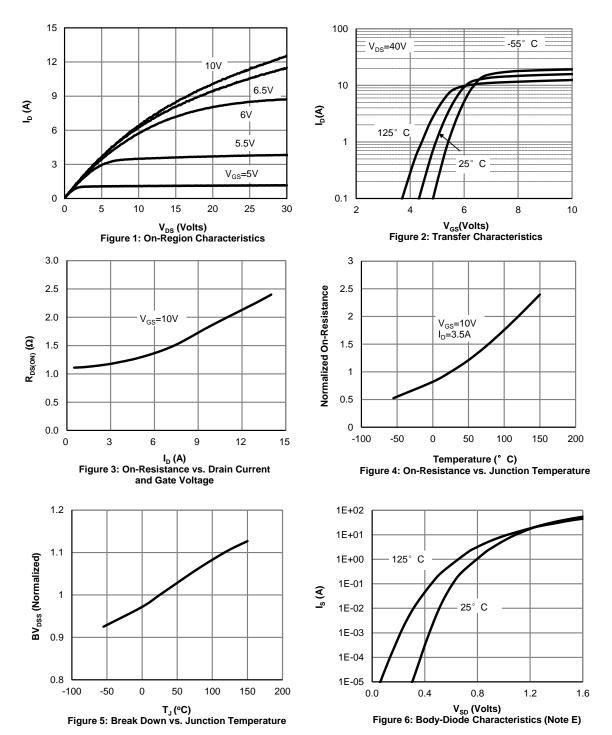
G. L=60mH,  $I_{AS}$ =3.5A,  $V_{DD}$ =150V,  $R_{G}$ =25 $\Omega$ , Starting  $T_{J}$ =25 $^{\circ}$  C

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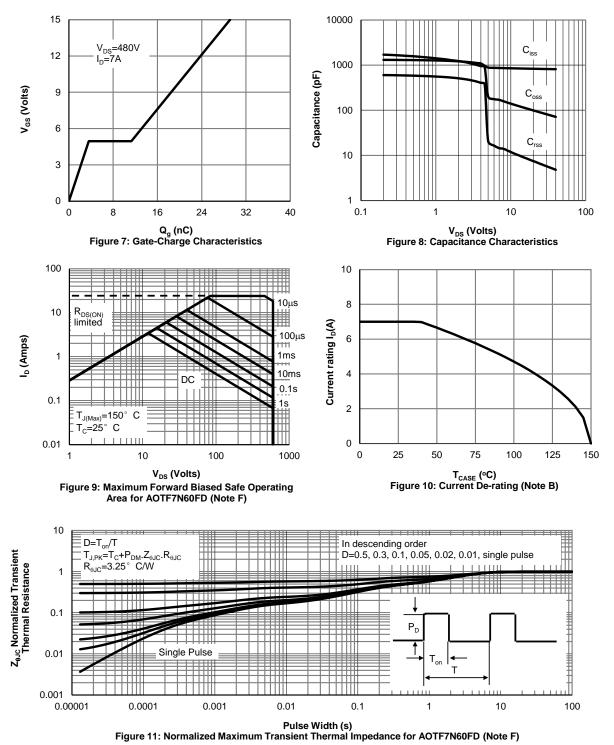


## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



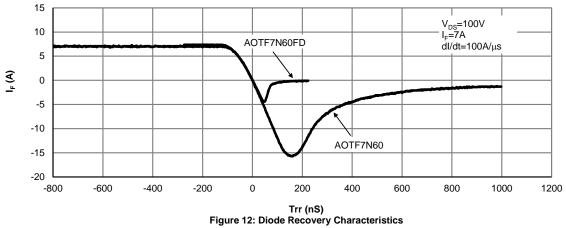


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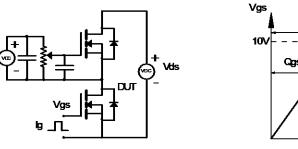


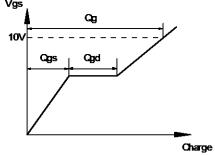
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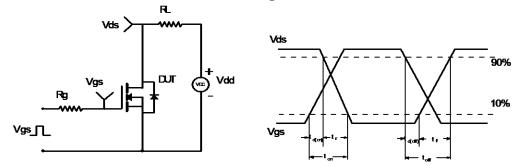


### Gate Charge Test Circuit & Wave form

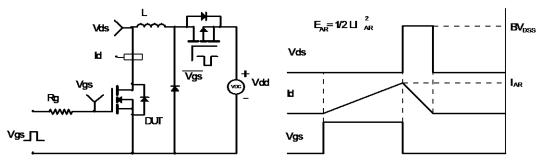




### Resistive Switching Test Circuit & Waveforms



### Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



### Diode Recovery Test Circuit & Waveforms

